

Title (en)

MOISTURE-CURABLE HOT MELT ADHESIVE

Title (de)

FEUCHTIGKEITSHÄRTBARER HEISSSCHMELZKLEBER

Title (fr)

ADHÉSIF THERMOFUSIBLE DURCISSABLE SOUS L'ACTION DE L'HUMIDITÉ

Publication

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Application

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Abstract (en)

[origin: WO2011068847A2] The present invention provides a method for producing a moisture-curable hot melt adhesive. This moisture-curable hot melt adhesive is environmentally friendly, is compatible with the components therein, has high initial adhesion strength, has long open time and has high heat resistance after moisture curing. The moisture-curable hot melt adhesive comprises a (A) urethane prepolymer having an isocyanate group at the terminus, comprising, a (A) urethane-modified rosin, and a (B) copolymer of ethylene and a (meth)acrylic acid derivative, wherein the urethane prepolymer is obtained by the reaction of polyol with an isocyanate compound.

IPC 8 full level

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